

APPLICATION DATA SHEET

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Application Information

Title Line One:: Interconnections with Electrically Conductive Adhesives:
Title Line Two:: Structures, Materials, Method and Their Applications
Total Drawing Sheets:: 4
Formal Drawings?: Yes
Application Type:: Regular Utility
Docket Number:: YO997-211US2

Continuity Information

This application is a::	Divisional
>Application One::	09/106,780
Filing Date::	June 30, 1998
Patent Number::	—

Prior Applications

Application One::	60/052,173
Filing Date::	10/July/1997
Country::	US
Priority Claimed::	Yes

2025 RELEASE UNDER E.O. 14176